

# MECHANICAL CASE OUTLINE

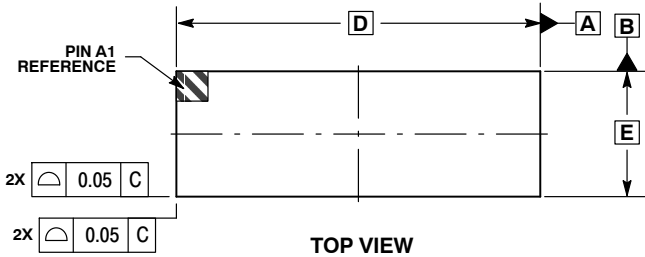
## PACKAGE DIMENSIONS



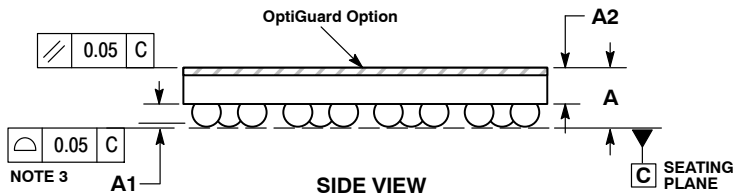
**WLCSP20, 4.01x1.38**  
CASE 567CL-01  
ISSUE O

DATE 26 JUL 2010

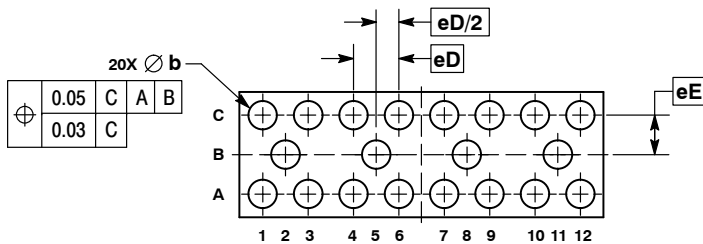
SCALE 4:1



TOP VIEW



SIDE VIEW

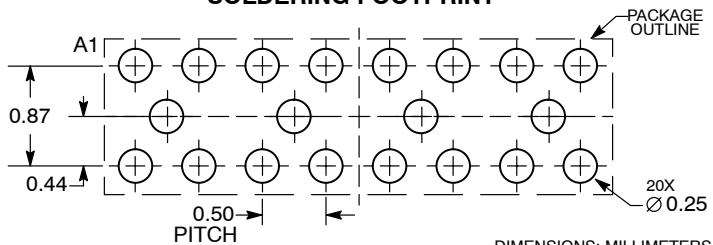


BOTTOM VIEW

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42 REF	
b	0.29	0.35
D	4.01 BSC	
E	1.38 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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